



SLVS349C - NOVEMBER 2001 - REVISED FEBRUARY 2003

# ULTRALOW-NOISE, HIGH PSRR, FAST RF 250-mA LOW-DROPOUT LINEAR REGULATORS

### FEATURES

- 250-mA Low-Dropout Regulator With EN
- Available in 1.8-V, 2.5-V, 2.8-V, 3-V, 3.3 V, and Adjustable
- High PSRR (65 dB at 10 kHz)
- Ultralow Noise (32 μV)
- Fast Start-Up Time (50 μs)
- Stable With a 2.2-µF Ceramic Capacitor
- Excellent Load/Line Transient
- Very Low Dropout Voltage (155 mV at Full Load, TPS79430)
- Available in MSOP8 and SOT223-6 Packages

## **APPLICATIONS**

- Cellular and Cordless Telephones
- VCOs
- RF
- Bluetooth<sup>™</sup>, Wireless LAN
- Handheld Organizers, PDA

## DESCRIPTION

The TPS794xx family of low-dropout (LDO) low-power linear voltage regulators features high power supply rejection ratio (PSRR), ultralow noise, fast start-up, and excellent line and load transient responses in small outline, MSOP8 PowerPAD™ and SOT223-6, packages. Each device in the family is stable with a small 2.2-µF ceramic capacitor on the output. The family uses an advanced, proprietary BiCMOS fabrication process to yield extremely low dropout voltages (e.g., 155 mV at 250 mA, TPS79430). Each device achieves fast start-up times (approximately 50  $\mu$ s with a 0.001- $\mu$ F bypass capacitor) while consuming very low quiescent current (170 µA typical). Moreover, when the device is placed in standby mode, the supply current is reduced to less than 1  $\mu$ A. The TPS79428 exhibits approximately 32  $\mu$ V<sub>RMS</sub> of output voltage noise with a 0.1-µF bypass capacitor. Applications with analog components that are noise sensitive, such as portable RF electronics, benefit from the high PSRR and low noise features as well as the fast response time.



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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### **ORDERING INFORMATION**

Тj	VOLTAGE	PACKAGE	PART NUMBER <sup>(1, 2)</sup>	SYMBOL	
		MEOD	TPS79401DGNR		
	Adjustable	MSOP	TPS79401DGNT	AXL	
	Aujustable	SOT222 6	TPS79401DCQR	D670401	
		501225-0	TPS79401DCQ	P379401	
		MSOD	TPS79418DGNR	A Y M	
	1 9 \/	MISOF	TPS79418DGNT		
	1.0 V	SOT223-6	TPS79418DCQR	D\$70/18	
		301223-0	TPS79418DCQ	F379410	
		MSOD	TPS79425DGNR		
	2.5 V 2.8 V	MISOF	TPS79425DGNT	AID	
		SOT223-6	TPS79425DCQR	D\$70425	
-40°C to 125°C			TPS79425DCQ	1 37 3423	
-40 0 10 125 0		MSOP	TPS79428DGNR	AVC	
			TPS79428DGNT	AIC	
		SOT223-6	TPS79428DCQR	D\$70429	
		501225-0	TPS79428DCQ	1 37 9420	
		MSOP	TPS79430DGNR		
	21/	MOOI	TPS79430DGNT	AID	
	5 V	COT222 C	TPS79430DCQR	P\$70/30	
		501225-0	TPS79430DCQ	1 37 9430	
		MSOP	TPS79433DGNR	ΔΥΕ	
	331/	MOOI	TPS79433DGNT		
	5.5 V	SOT223-6	TPS79433DCQR	P\$70433	
		001220-0	TPS79433DCQ	F 37 9433	

(1) The DGNR and DCQR indicates tape and reel of 2500 parts.

(2) The DGNT indicates tape and reel of 250 parts.

#### **ABSOLUTE MAXIMUM RATINGS**

over operating free-air temperature range unless otherwise noted (1)

	TPS79401, TPS79425, TPS79418 TPS79428, TPS79430, TPS79433
Input voltage range <sup>(2)</sup>	-0.3 V to 6 V
Voltage range at EN	–0.3 V to V <sub>I</sub> + 0.3 V
Voltage on OUT	-0.3 V to 6 V
Peak output current	Internallylimited
ESD rating, HBM	2 kV
ESD rating, CDM	500 V
Continuous total power dissipation	See Dissipation Rating Table
Operating virtual junction temperature range, TJ	-40°C to 150°C
Storage temperature range, T <sub>stg</sub>	-65°C to 150°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values are with respect to network ground terminal.



## PACKAGE DISSIPATION RATINGS

PACKAGE	AIR FLOW (CFM)	R <sub>θ</sub> JC (°C/W)	R <sub>θ</sub> JA (° <b>C/W)</b>	T <sub>A</sub> ≤ 25°C POWER RATING	T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 85°C POWER RATING
	0	8.47	55.09	2.27 W	1.45 W	1.18 W
DGN	150	8.21	49.97	2.50 W	1.60 W	1.30 W
	250	8.20	48.10	2.60 W	1.66 W	1.35 W



CONDITIONS PACKAGE		PCB AREA	θJA		
1	SOT223	4in <sup>2</sup> Top Side Only	53°C/W		
2	SOT223	0.5in <sup>2</sup> Top Side Only	110°C/W		

#### Figure 1. SOT223 Power Dissipation

### **ELECTRICAL CHARACTERISTICS**

over recommended operating free-air temperature range EN =  $V_{I}$ ,  $T_{J}$  = -40 to 125 °C,  $V_{I}$  =  $V_{O(typ)}$  + 1 V,  $I_{O}$  = 1 mA,  $C_{O}$  = 10  $\mu$ F,  $C_{(byp)}$  = 0.01  $\mu$ F (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT	
VI	Input voltage(1)				2.7		5.5	V
lO	Continuous output current(2	:)			0		250	mA
ТJ	Operating junction temperat	ure			-40		125	°C
		TD070404	TJ = 25°C			٧O		
		1F379401	0 μA < IO < 250 mA,	1.22 V ≤ V <sub>O</sub> ≤ 5.5 V(3)	0.97 V <sub>O</sub>		1.03 V <sub>O</sub>	
		TD970449	T <sub>J</sub> = 25°C			1.8		V
		1F3/9410	$0 \mu\text{A} < \text{I}_{O} < 250 \text{mA},$	$2.8~V \leq V_{I} \leq 5.5~V$	1.746		1.854	
		TPS79425	TJ = 25°C			2.5		
	Output voltage		0 μA < IO < 250 mA,	3.5 V < Vj < 5.5 V	2.425		2.575	
		TPS79428	TJ = 25°C			2.8		
			0 μA < IO < 250 mA,	3.8 V < Vj < 5.5 V	2.716		2.884	
		TPS79430	TJ = 25°C			3		
			0 μA < I <sub>O</sub> < 250 mA,	4 V < V <sub>I</sub> < 5.5 V	2.91		3.09	
		TPS79433	TJ = 25°C			3.3		
			0 μA < IO < 250 mA,	4.3 V < V <sub>I</sub> < 5.5 V	3.201		3.399	
Quiescent current (GND current)		0 μA < IO < 250 mA,	$T_J = 25^{\circ}C$		170			
		0 μA < IO < 250 mA				220	μА	
	Loadregulation		0 μA < IO < 250 mA,	$T_J = 25^{\circ}C$		10		mV

(1) To calculate the minimum input voltage for your maximum output current, use the following formula:  $V_{I}(min) = V_{O}(max) + V_{DO}(max load)$ (2) Continuous output current and operating junction temperature are limited by internal protection circuitry, but it is not recommended that the device operate under conditions beyond those specified in this table for extended periods of time.

(3) The minimum IN operating voltage is 2.7 V or  $V_{O(typ)}$  + 1 V, whichever is greater. The maximum IN voltage is 5.5 V. The maximum continuous output current is 250 mA.



#### **ELECTRICAL CHARACTERISTICS (continued)**

over recommended operating free-air temperature range EN =  $V_{I}$ ,  $T_{J}$  = -40 to 125 °C,  $V_{I}$  =  $V_{O(typ)}$  + 1 V,  $I_{O}$  = 1 mA,  $C_{O}$  = 10  $\mu$ F,  $C_{(byp)}$  = 0.01  $\mu$ F (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN TYP	MAX	UNIT	
Output voltage line regula	Output voltage line regulation		$T_J = 25^{\circ}C$	0.05		0/ \/	
$(\Delta V_O/V_O)^{(4)}$		V <sub>O</sub> + 1 V < V <sub>I</sub> ≤ 5.5 V			0.12	%/V	
			$C_{(byp)} = 0.001  \mu F$	55		μVRMS	
	070400)	BW = 100 Hz to 100 kHz,	$C_{(byp)} = 0.0047 \mu\text{F}$	36			
Output hoise voitage (1P3	579428)	IO = 250 mA, TJ = 25°C	$C_{(byp)} = 0.01  \mu F$	33			
			$C_{(byp)} = 0.1  \mu F$	32			
			C <sub>(byp)</sub> = 0.001 µF	50			
Time, start-up (TPS79428	3)	$R_L - 14 \Omega$ , $C_0 = 1 \mu$ F, T <sub>1</sub> = 25°C	$C_{(byp)} = 0.0047 \mu F$	70		μs	
		19-20 0	C <sub>(byp)</sub> = 0.01 µF	100			
Output current limit		$V_{O} = 0 V(3)$		925		mA	
Standby current		EN = 0 V,	2.7 V < V <sub>I</sub> < 5.5 V	0.07	1	μΑ	
High level enable input vo	High level enable input voltage		2.7 V < V <sub>I</sub> < 5.5 V			V	
Low level enable input vo	Low level enable input voltage		2.7 V < V <sub>I</sub> < 5.5 V		0.7	V	
Input current (EN)	Input current (EN)		EN = 0		1	μA	
Input current (FB)	Input current (FB)		FB = 1.8 V		1	μΑ	
		$f = 100 \text{ Hz}, T_J = 25^{\circ}\text{C},$	I <sub>O</sub> = 10 mA	65			
Power supply ripple	TDC70429	$f = 100 \text{ Hz}, \text{ T}_{J} = 25^{\circ}\text{C},$	I <sub>O</sub> = 250 mA	65		dB	
rejection	1P579426	$f = 10 \text{ kHz},  T_J = 25^{\circ}\text{C},$	I <sub>O</sub> = 250 mA	60			
		$f = 100 \text{ kHz}, T_J = 25^{\circ}C,$	IO = 250 mA	40			
	TDC70429	I <sub>O</sub> = 250 mA,	$T_J = 25^{\circ}C$	155			
	1P379428	I <sub>O</sub> = 250 mA			210		
Dropout voltage(5)	TD970420	$I_{O} = 250 \text{ mA}, T_{J} = 25^{\circ}C$	_	155		210 mV 200 mV	
	1F379430	I <sub>O</sub> = 250 mA	_		210		
	TPS79433	$I_{O} = 250 \text{ mA}, T_{J} = 25^{\circ}C$		145			
		I <sub>O</sub> = 250 mA			200		
UVLO threshold		V <sub>CC</sub> rising		2.25	2.65	V	
UVLO hysteresis	UVLO hysteresis			100		mV	

(4) If  $V_0 \le 2.5$  V then  $V_{Imin} = 2.7$  V,  $V_{Imax} = 5.5$  V:

Line regulation (mV) = 
$$(\%/V) \times \frac{V_O(V_{Imax} - 2.7 V)}{100} \times 1000$$

If  $V_O \ge 2.5$  V then  $V_{Imin} = V_O + 1$  V,  $V_{Imax} = 5.5$  V.

(5) IN voltage equals V<sub>O</sub>(typ) – 100 mV; The TPS78418 and TPS79425 dropout voltage are limited by the input voltage range limitations.



#### **Terminal Functions**

	TERMINA	L				
NAME	DGN (MSOP)	DCQ (SOT223)	I/O	DESCRIPTION		
BYP	4	5		An external bypass capacitor, connected to this terminal, in conjunction with an internal resistor, creates a low-pass filter to further reduce regulator noise. Not available on the TPS79401DCQ package.		
EN	6	1	I	The EN terminal is an input which enables or shuts down the device. When EN goes to a logic high, the device is enabled. When the device goes to a logic low, the device is in shutdown mode.		
FB	3	5	I	This terminal is the feedback input voltage for the adjustable device.		
GND	5	3, 6		Regulator ground		
VIN	8	2	I	The V <sub>IN</sub> terminal is the input to the device.		
NC	2, 7			Regulatorground		
VOUT	1	4	0	The VOUT terminal is the regulated output of the device.		

#### FUNCTIONAL BLOCK DIAGRAM—ADJUSTABLE VERSION



#### FUNCTIONAL BLOCK DIAGRAM—FIXED VERSION





### **TYPICAL CHARACTERISTICS**





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#### **TYPICAL CHARACTERISTICS**







Figure 14





Figure 15

TPS79425 POWER UP / POWER DOWN





#### **TYPICAL CHARACTERISTICS**

TPS79401







TPS79428 TYPICAL REGIONS OF STABILITY EQUIVALENT SERIES RESISTANCE (ESR)



TPS79428 TYPICAL REGIONS OF STABILITY EQUIVALENT SERIES RESISTANCE (ESR)





#### **APPLICATION INFORMATION**

The TPS794xx family of low-dropout (LDO) regulators has been optimized for use in noise-sensitive battery-operated equipment. The device features extremely low dropout voltages, high PSRR, ultralow output noise, low quiescent current (170  $\mu$ A typically), and enable input to reduce supply currents to less than 1  $\mu$ A when the regulator is turned off.

A typical application circuit is shown in Figure 23.



<sup>†</sup> Not Available on the TPS79401 in the SOT223–6 package.



### **EXTERNAL CAPACITOR REQUIREMENTS**

A  $0.1-\mu$ F or larger ceramic input bypass capacitor, connected between IN and GND and located close to the TPS794xx, is required for stability. It improves transient response, noise rejection, and ripple rejection. A higher-value electrolytic input capacitor may be necessary if large, fast-rise-time load transients are anticipated and the device is located several inches from the power source.

Like all low dropout regulators, the TPS794xx requires an output capacitor connected between OUT and GND to stabilize the internal control loop. The minimum recommended capacitance is 2.2  $\mu$ F. Any 2.2  $\mu$ F or larger ceramic capacitor is suitable.

The internal voltage reference is a key source of noise in an LDO regulator. The TPS794xx has a BYPASS pin which is connected to the voltage reference through a 250-k $\Omega$  internal resistor. The 250-k $\Omega$  internal resistor, in conjunction with an external bypass capacitor connected to the BYPASS pin, creates a low pass filter to reduce the voltage reference noise and, therefore, the noise at the regulator output. In order for the regulator to operate properly, the current flow out of the BYPASS pin must be at a minimum, because any leakage current creates an IR drop across the internal resistor thus creating an output error. Therefore, the bypass capacitor must have minimal leakage current.

For example, the TPS79428 exhibits only 32  $\mu$ V<sub>RMS</sub> of output voltage noise using a 0.1- $\mu$ F ceramic bypass capacitor and a 2.2- $\mu$ F ceramic output capacitor. Note that the output starts up slower as the bypass capacitance increases due to the RC time constant at the bypass pin that is created by the internal 250-k $\Omega$  resistor and external capacitor.



(2)

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### BOARD LAYOUT RECOMMENDATION TO IMPROVE PSRR AND NOISE PERFORMANCE

To improve ac measurements like PSRR, output noise, and transient response, it is recommended that the board be designed with separate ground planes for  $V_{IN}$  and  $V_{OUT}$ , with each ground plane connected only at the ground pin of the device. In addition, the ground connection for the bypass capacitor should connect directly to the ground pin of the device.





#### POWER DISSIPATION AND JUNCTION TEMPERATURE

Specified regulator operation is assured to a junction temperature of 125°C; the maximum junction temperature should be restricted to 125°C under normal operating conditions. This restriction limits the power dissipation the regulator can handle in any given application. To ensure the junction temperature is within acceptable limits, calculate the maximum allowable dissipation,  $P_{D(max)}$ , and the actual dissipation,  $P_{D}$ , which must be less than or equal to  $P_{D(max)}$ .

The maximum-power-dissipation limit is determined using the following equation:

$$P_{D(max)} = \frac{T_{J}max - T_{A}}{R_{\theta JA}}$$
(1)

where:

T<sub>J</sub>max is the maximum allowable junction temperature.

 $R_{\theta JA}$  is the thermal resistance junction-to-ambient for the package. See power dissipation table and Figure 1.

T<sub>A</sub> is the ambient temperature.

The regulator dissipation is calculated using:

$$\mathsf{P}_{\mathsf{D}} = \left(\mathsf{V}_{\mathsf{I}} - \mathsf{V}_{\mathsf{O}}\right) \times \mathsf{I}_{\mathsf{O}}$$

Power dissipation resulting from quiescent current is negligible. Excessive power dissipation triggers the thermal protection circuit.

### **REGULATOR MOUNTING**

The tab of the SOT223-6 package is electrically connected to ground. For best thermal performance, the tab of the surface-mount version should be soldered directly to a circuit-board copper area. Increasing the copper area improves heat dissipation.

Although the tab of the SOT223–6 is electrically grounded, it is not intended to carry any current. The copper pad that acts as a heat sink should be isolated from the rest of the circuit to prevent current flow through the device from the tab to the ground pin. Solder pad footprint recommendations for the devices are presented in an application bulletin *Solder Pad Recommendations for Surface-Mount Devices*, literature number AB–132, available from the TI web site (www.ti.com).



#### PROGRAMMING THE TPS79401 ADJUSTABLE LDO REGULATOR

The output voltage of the TPS79401 adjustable regulator is programmed using an external resistor divider as shown in Figure 25. The output voltage is calculated using:

$$V_{O} = V_{ref} \times \left(1 + \frac{R1}{R2}\right)$$
(3)

where

 $V_{ref}$  = 1.2246 V typ (the internal reference voltage)

Resistors R1 and R2 should be chosen for approximately 40- $\mu$ A divider current. Lower value resistors can be used for improved noise performance, but the device wastes more power. Higher values should be avoided as leakage current at FB increases the output voltage error. The recommended design procedure is to choose R2 = 30.1 k $\Omega$  to set the divider current at 40  $\mu$ A, C1 = 15 pF for stability, and then calculate R1 using:

$$R1 = \left(\frac{V_{O}}{V_{ref}} - 1\right) \times R2$$
(4)

In order to improve the stability of the adjustable version, it is suggested that a small compensation capacitor be placed between OUT and FB. For voltages <1.8 V, the value of this capacitor should be 100 pF. For voltages >1.8 V, the approximate value of this capacitor can be calculated as:

$$C1 = \frac{(3 \times 10^{-7}) \times (R1 + R2)}{(R1 \times R2)}$$
(5)

The suggested value of this capacitor for several resistor ratios is shown in the table below. If this capacitor is not used (such as in a unity-gain configuration) or if an output voltage <1.8 V is chosen, then the minimum recommended output capacitor is 4.7  $\mu$ F instead of 2.2  $\mu$ F.



OUTPUT VOLTAGE PROGRAMMING GUIDE

OUTPUT VOLTAGE	R1	R2	C1	
2.5 V	$31.6  k\Omega$	30.1 kΩ	22 pF	
3.3 V	49.9 kΩ	30.1 kΩ	15 pF	
3.6 V	59 kΩ	30.1 kΩ	15 pF	

<sup>†</sup> Not Available on the DCQ package.

Figure 25. TPS79401 Adjustable LDO Regulator Programming

#### **REGULATOR PROTECTION**

The TPS794xx PMOS-pass transistor has a built-in back diode that conducts reverse current when the input voltage drops below the output voltage (e.g., during power down). Current is conducted from the output to the input and is not internally limited. If extended reverse voltage operation is anticipated, external limiting might be appropriate.

The TPS794xx features internal current limiting and thermal protection. During normal operation, the TPS794xx limits output current to approximately 925 mA. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package or the absolute maximum voltage rating of the device. If the temperature of the device exceeds approximately 165°C, thermal-protection circuitry shuts it down. Once the device has cooled down to below approximately 140°C, regulator operation resumes.

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### **MECHANICAL DATA**

#### DCQ (R-PDSO-G6)

PLASTIC SMALL-OUTLINE



NOTES:A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Controlling dimension in inches

Body length and width dimensions are determined at the outermost extremes of the plastic body exclusive of mold flash, tie bar burrs, gate burrs, and interlead flash, but including any mismatch between the top and the bottom of the plastic body.

/E. Lead width dimensions does not include dambar protrusion.

F. Lead width and thickness dimensions apply to solder plated leads.

- G. Interlead flash allow 0.008 inch max.
- H. Gate burr/protrusion max. 0.006 inch.



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#### **MECHANICAL DATA**

#### DGN (S-PDSO-G8)

#### PowerPAD<sup>™</sup> PLASTIC SMALL-OUTLINE PACKAGE



NOTES:A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions include mold flash or protrusions.

D. The package thermal performance may be enhanced by attaching an external heat sink to the thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected leads.

E. Falls within JEDEC MO-187

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